

SSS4N60B

600V N-Channel MOSFET

General Description

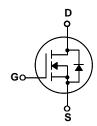
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies.

Features

- 2.3A, 600V, $R_{DS(on)}$ = 2.5 Ω @V_{GS} = 10 V Low gate charge (typical 22 nC)
- Low Crss (typical 14 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		SSS4N60B	Units	
V _{DSS}	Drain-Source Voltage		600	V	
I _D	Drain Current - Continuous (T _C = 25°C)		2.3	А	
	- Continuous (T _C = 100°C)		1.5	А	
I _{DM}	Drain Current - Pulsed	(Note 1)	9.2	А	
V_{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	240	mJ	
I _{AR}	Avalanche Current	(Note 1)	2.3	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	3.3	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	3.0	V/ns	
P _D	Power Dissipation (T _C = 25°C)		33	W	
	- Derate above 25°C		0.26	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.79	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W	

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	racteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced	to 25°C		0.65		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600 V, V _{GS} = 0 V				10	μΑ
		V _{DS} = 480 V, T _C = 125°C				100	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 1.15 A			2.0	2.5	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 1.15 A	(Note 4)		3.2		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			710 65 14	920 85 19	pF pF
	ng Characteristics						P.
t _{d(on)}	Turn-On Delay Time	V_{DD} = 300 V, I_{D} = 4.0 A, R_{G} = 25 Ω (Note 4, 5)			20	50	ns
t _r	Turn-On Rise Time				55	120	ns
t _{d(off)}	Turn-Off Delay Time				70	150	ns
t _f	Turn-Off Fall Time				55	120	ns
Qg	Total Gate Charge	$V_{DS} = 480 \text{ V}, I_D = 4.0 \text{ A},$			22	29	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V (Note 4, 5)			4.8		nC
Q _{gd}	Gate-Drain Charge				8.5		nC
Drain-S	ource Diode Characteristics a	nd Maximum Ratings	S				
I _S	Maximum Continuous Drain-Source Diode Forward Current				2.3	Α	
I _{SM}	Maximum Pulsed Drain-Source Diode F					9.2	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.3 \text{ A}$				1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 4.0 \text{ A},$	(NI=4 - A)		330		ns
Q _{rr}	Reverse Recovery Charge	$dI_{F} / dt = 100 A/\mu s$	(Note 4)		2.67		μC

- **Notes:** 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 83mH, I_{AS} = 2.3A, V_{DD} = 50V, R_{G} = 25 Ω . Starting T_{J} = 25°C 3. I_{SD} ≤ 4.0A, di/dt ≤ 200A/ μ s, V_{DD} ≤ BV $_{DSS}$, Starting T_{J} = 25°C 4. Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

Typical Characteristics

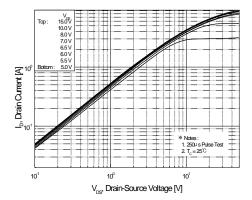


Figure 1. On-Region Characteristics

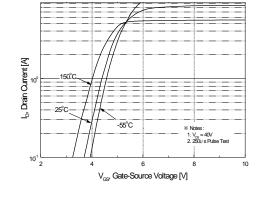


Figure 2. Transfer Characteristics

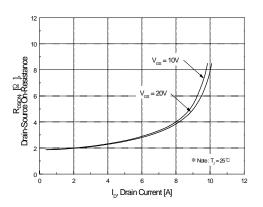


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

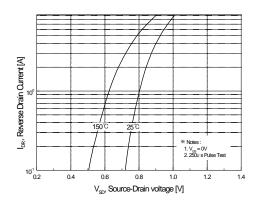


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

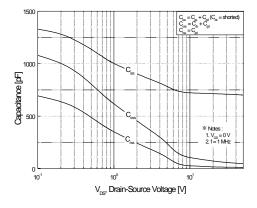


Figure 5. Capacitance Characteristics

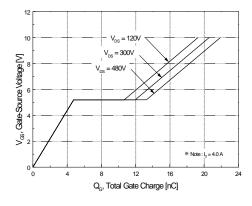


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)

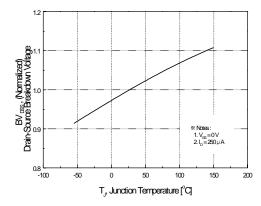


Figure 7. Breakdown Voltage Variation vs Temperature

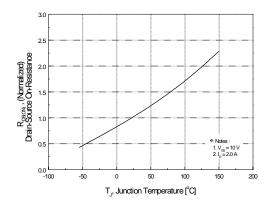


Figure 8. On-Resistance Variation vs Temperature

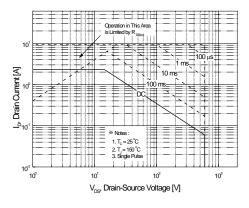


Figure 9. Maximum Safe Operating Area

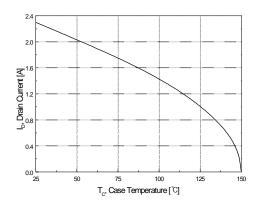


Figure 10. Maximum Drain Current vs Case Temperature

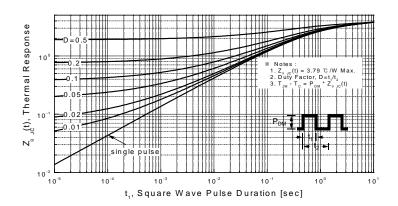
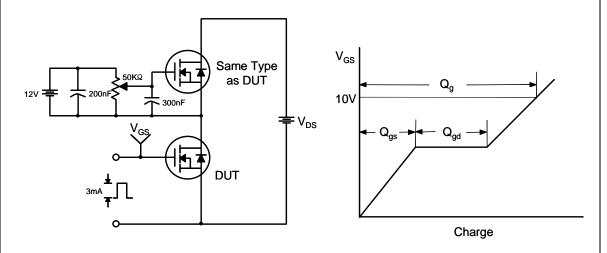


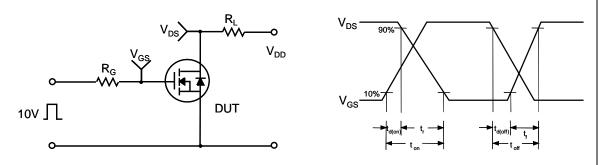
Figure 11. Transient Thermal Response Curve

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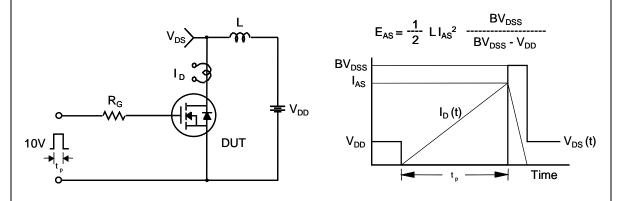
Gate Charge Test Circuit & Waveform



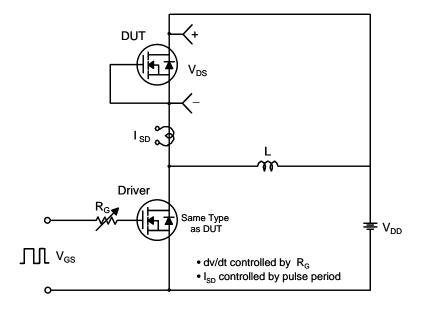
Resistive Switching Test Circuit & Waveforms

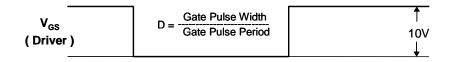


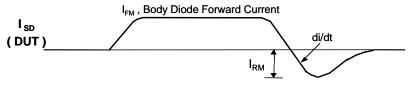
Unclamped Inductive Switching Test Circuit & Waveforms



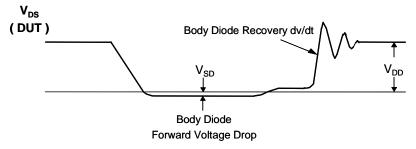
Peak Diode Recovery dv/dt Test Circuit & Waveforms

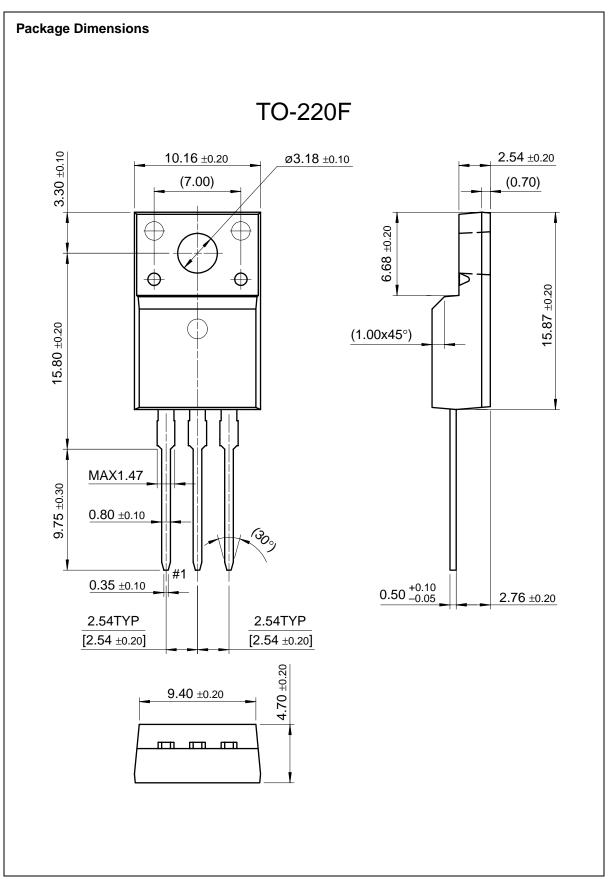






Body Diode Reverse Current





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